

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-14 (Canceled).

Claim 15 (Currently Amended): An inductive device comprising:

an inorganic sintered core board;

a plurality of band-shaped conductor patterns ~~formed~~ having exposed end portions on front and rear surfaces of said inorganic sintered core board; and

a plurality of bridging conductor patterns formed on cut surfaces of said inorganic sintered core board sliced transversely with respect to said band-shaped conductor patterns so that the exposed end portions of said band-shaped conductor patterns on each of said ~~cut~~ front and rear surfaces of said inorganic sintered core board are connected to one another by said plurality of bridging conductor patterns to thereby provide at least one helical coil.

Claim 16 (Currently Amended): An inductive device comprising:

an inorganic sintered core board;

a plurality of band-shaped conductor patterns ~~formed~~ having exposed end portions on front and rear surfaces of said inorganic sintered core board;

electrically insulating layers formed on said front and rear surfaces of said inorganic sintered core board so that said band-shaped conductor patterns are covered with said electrically insulating layers; and

a plurality of bridging conductor patterns formed on cut surfaces of said inorganic sintered core board sliced transversely with respect to said band-shaped conductor patterns so that the exposed end portions of said band-shaped conductor patterns on each of said ~~cut~~ front

and rear surfaces of said inorganic sintered core board are connected to one another by said plurality of bridging conductor patterns to thereby provide at least one helical coil.

Claims 17-18 (Canceled).

Claim 19 (Currently Amended): An inductive device according to any one of Claims 15 ~~through 18~~ or 16, wherein a surface of each inorganic sintered core board on which said band-shaped conductor patterns are formed is smooth.

Claim 20 (Currently Amended): A method of producing an inductive device, comprising ~~the steps of~~:

forming a plurality of band-shaped conductor patterns having exposed end portions on front and rear surfaces of a plurality of inorganic sintered core boards and integrally laminating said plurality of inorganic sintered core boards through electrically insulating layers to form a laminated board (lamination ~~step~~);

slicing said laminated board obtained in the lamination transversely with respect to said band-shaped conductor patterns to thereby form laminated sliced bodies (slicing ~~step~~);

forming a plurality of bridging conductor patterns on cut surfaces of each laminated sliced body obtained in the slicing ~~step~~ so that the exposed end portions of said band-shaped conductor patterns on each of said ~~cut~~ front and rear surfaces of said laminated sliced body are connected to one another by individual of said plurality of bridging conductor patterns (bridging conductor formation ~~step~~); and

separating each laminated sliced body into individual chips so that each chip includes at least one helical coil formed from said band-shaped conductor patterns and said plurality of bridging conductor patterns (separation ~~step~~).

Claim 21 (Currently Amended): A method of producing an inductive device, comprising ~~the steps of~~:

forming a plurality of band-shaped conductor patterns and electrically insulating layers for covering said plurality of band-shaped conductor patterns having exposed end portions on front and rear surfaces of a plurality of inorganic sintered core boards and integrally laminating said plurality of inorganic sintered core boards through adhesive layers to form a laminated board (lamination ~~step~~);

slicing said laminated board obtained in the lamination ~~step~~ transversely with respect to said band-shaped conductor patterns to thereby form laminated sliced bodies (slicing ~~step~~);

forming a plurality of bridging conductor patterns on cut surfaces of each laminated sliced body obtained in the slicing ~~step~~ so that the exposed end portions of said band-shaped conductor patterns on each of said ~~cut~~ front and rear surfaces of said laminated sliced body are connected to one another by individual of said plurality of bridging conductor patterns (bridging conductor formation ~~step~~); and

separating each laminated sliced body into individual chips so that each chip includes at least one helical coil formed from said band-shaped conductor patterns and said plurality of bridging conductor patterns (separation ~~step~~).

Claims 22-24 (Canceled).

Claim 25 (Currently Amended): A method of producing an inductive device according to any one of Claims 20 ~~through 24~~ or 21, wherein each electrically insulating layer is polished to adjust the thickness of said inductive device.

Claim 26 (Canceled).

Claim 27 (Currently Amended): A method of producing an inductive device according to any one of Claims 20 ~~through 24~~ or 21, wherein said cut surfaces of said laminated sliced bodies after the slicing ~~step~~ are polished to adjust the thickness of said inductive device.

Claim 28 (Currently Amended): A method of producing an inductive device according to any one of Claims 20 ~~through 24~~ or 21, wherein an inorganic sintered body used in each inorganic sintered core board is made of a porous ceramic substance.

Claim 29 (Currently Amended): A method of producing an inductive device according to any one of Claims 20 ~~through 24~~ or 21, wherein an inorganic sintered body used in each inorganic sintered core board is made of a magnetic substance.

Claim 30 (Currently Amended): An inductive device comprising:  
a core board;  
a plurality of conductive layers, each layer including a plurality of band-shaped conductor patterns ~~formed~~ having exposed end portions on a surface front and rear surfaces of said core board;

a plurality of bridging conductor patterns formed on ~~cut surface~~ a side surface of said core board, ~~sliced transversely with respect to said band-shaped conductor patterns so that exposed end portions of said band-shaped conductor patterns on each of said front and rear surfaces cut surface of said core board are being~~ connected to one another by said plurality of bridging conductor patterns to thereby provide at least one helical coil.

Claim 31 (Previously Presented): The inductive device as claimed in claim 30, wherein said conductive layers are formed on front and rear surfaces of said core board.

Claim 32 (Previously Presented): The inductive device as claimed in claim 30, wherein a plurality of core boards are provided, said conductive layer is formed on one surface of said core board, and the plural core boards are laminated through a insulating layer.

Claim 33 (Previously Presented): The inductive device as claimed in claim 30, wherein said core board is inorganic sintered core board.

Claim 34 (Previously Presented): The inductive device as claimed in claim 30, wherein said core board is an organic core board having filler.

Claim 35 (Previously Presented): A method of producing an inductive device, comprising ~~the steps of~~:

forming a plurality of band-shaped conductor patterns having exposed end portions on ~~at least one surface~~ front and rear surfaces of each of core boards;

integrally laminating the core boards through electrically insulating layers to form a laminated board,

slicing said laminated board transversely with respect to said band-shaped conductor patterns;

forming a plurality of bridging conductor patterns on a cut surface of the sliced laminated board, so that the exposed end portions of said band-shaped conductor patterns on

the ~~ent~~ front and rear surface are connected to one another by individual of the plurality of  
bridging conductor patterns; and

separating into individual chips so that each chip includes at least one helical coil  
formed ~~form~~ from the band-shaped conductor patterns and the plurality of bridging conductor  
patterns.